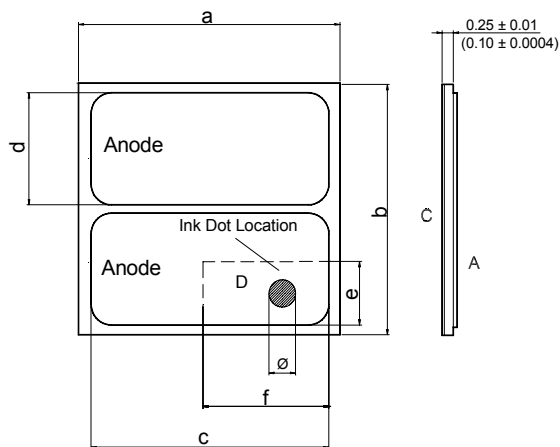
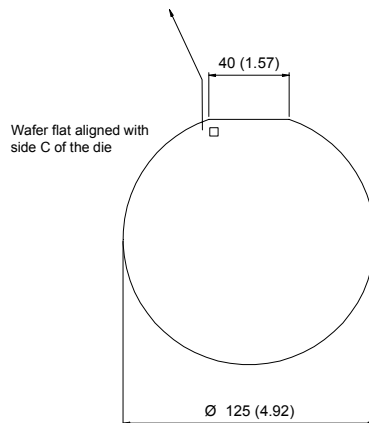


SCHOTTKY DIE 200 x 200 mils (Monolithic Dual)



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
2. CONTROLLING DIMENSION: (INCH).
3. DIMENSIONS AND TOLERANCES:
 - a = 5.08 + 0, - 0.05
(0.2 + 0, - 0.002)
 - b = 5.08 + 0, - 0.05
(0.2 + 0, - 0.002)
 - c = 4.92 + 0, - 0.003
(0.193 + 0, - 0.0001)
 - d = 2.43 + 0, - 0.003
(0.095 + 0, - 0.0001)
 - e = 1.11 + 0, - 0.003
(0.044 + 0, - 0.0001)
 - f = 2.36 + 0, - 0.003
(0.093 + 0, - 0.0001)
 - Ø = 0.7 ± 0.1
(0.03 ± 0.004)
4. LETTER DESIGNATION:
 - A = Anode (Top Metal)
 - C = Cathode (Back Metal)
 - D = Reject Ink Dot (only on non-conforming dies)
5. SAWING:
 - Recommended Blade
 - SEMITEC S1025 QS00 Blade



NOT TO SCALE

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Max. I _R @ 25°C (mA)	(*) Max. V _F @ I _F (V)
SC202 S 020A5	150	20	8	0.42 V @ 40A per die, T _J = 25°C
SC202 S 030A5	150	30	2	0.46V @ 30A per die, T _J = 25°C
SC202 S 045A5	150	45	2	0.51 V @ 20A per die, T _J = 25°C
SC202 S 060A5	150	60	2	0.54V @ 15A per die, T _J = 25°C
SC202 H 100A5	150	100	0.55	0.69 V @ 10A per die, T _J = 25°C

(*) For reference only, V_F do not include voltage drop across wire bonding resistance

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC202..... A 5..	Bondable	–	Al/Si 30 kÅ	–	Ti 1 kÅ	Ni 4 kÅ	Ag 6 kÅ

Visual Inspection : see IR internal Spec. # 6373-2064

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

Device #	Description	Minimum Order Quantity Wafer in Sale Package
SC202..... 5B .	Inked Probed Unsawn Wafer (Wafer in Box)	48

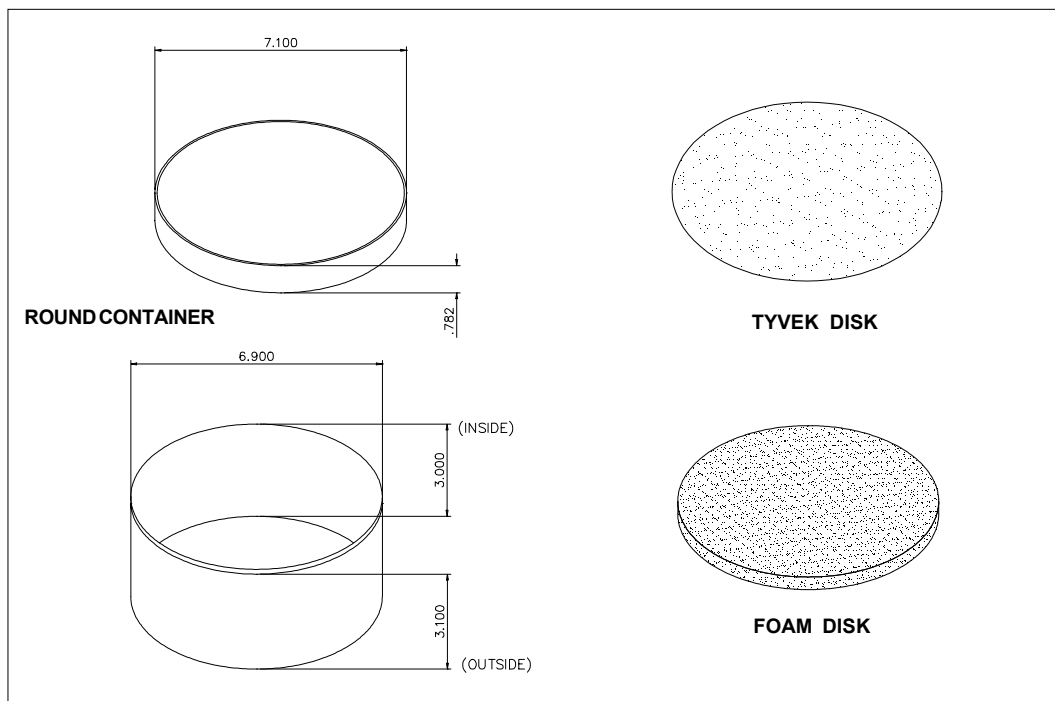
Ordering Information Table

Device Code							
SC	202	S	060	A	5	B	T
①	②	③	④	⑤	⑥	⑦	⑧

- 1** - Schottky Die
- 2** - Chip Dimension in Mils: 200 x 200 Dual Monolithic
- 3** - Process (see Electrical Characteristics Table)
- 4** - Voltage code: Code = V_{RRM}
- 5** - Chip surface metallization (Al)
- 6** - Wafer Diameter in inches
- 7** - Packaging: B = inked probed unsawn wafers (in box)
- 8** - Thickness (omitted if 14 mils, T for 10 mils Die)

H = 830 Process
 R = OR'ing Process
 S = Standard Process

Wafer in Box



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EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, U.K. Tel: ++ 44 1883 732020. Fax: ++ 44 1883 733408.
IR CANADA: 15 Lincoln Court, Brampton, Markham, Ontario L6T3Z2. Tel: (905) 453 2200. Fax: (905) 475 8801.
IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg. Tel: ++ 49 6172 96590. Fax: ++ 49 6172 965933.
IR ITALY: Via Liguria 49, 10071 Borgaro, Torino. Tel: ++ 39 11 4510111. Fax: ++ 39 11 4510220.
IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo, Japan 171. Tel: 81 3 3983 0086.
IR SOUTHEAST ASIA: 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994. Tel: ++ 65 838 4630.
IR TAIWAN: 16 Fl. Suite D.207, Sec. 2, Tun Haw South Road, Taipei, 10673, Taiwan. Tel: 886 2 2377 9936.

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Data and specifications subject to change without notice.